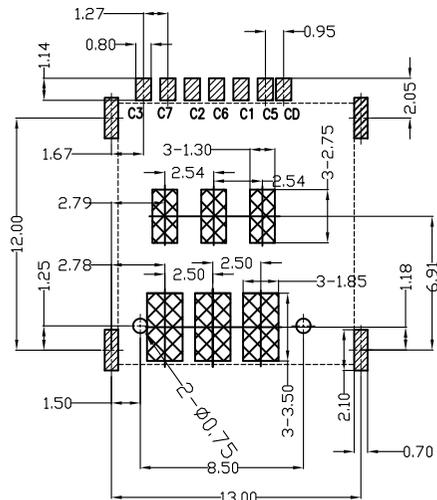
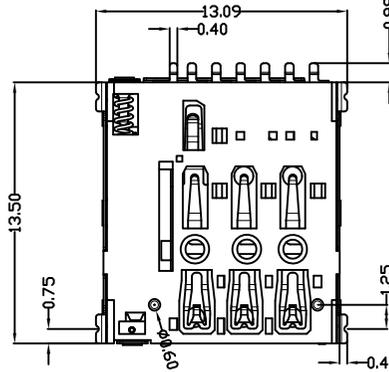
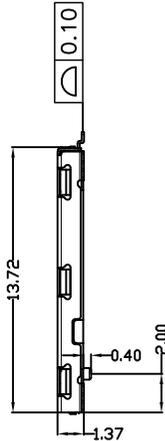
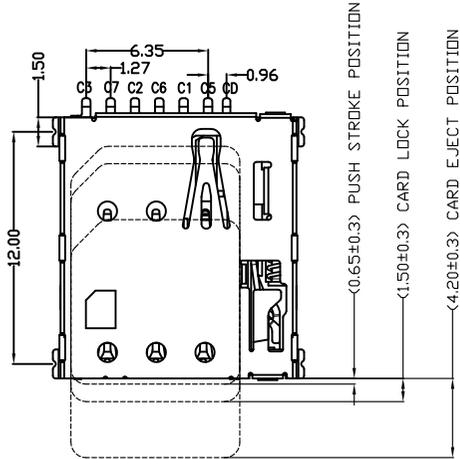
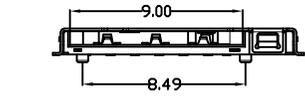
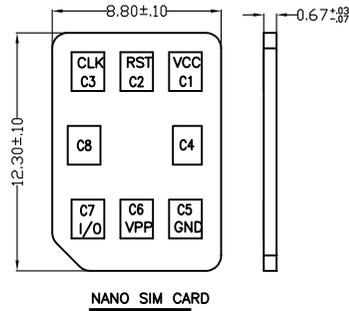


RoHS Compliant



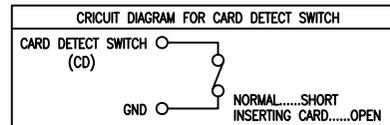
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

PAD
 KEEP OUT AREA



NANO SIM CARD

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	GND
C5	VPP
C6	I/O
C7	



NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:100mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5°C, 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40°C~+85°C;
Humidity 80% R.H MAX

深圳市敏连达科技有限公司 Shenzhen Minlianda Technology Co.,Ltd.		品名 (ITEM NO)	NANO SIM PUSH 1.37H 带CD PIN 带柱		
		料号 (PART NO)	MLD-NANO-7P-H1.37-S		
单位 (UNIT): MM	未注公差 TOLERANCE UNSPECIFIED	版次 (REV): A/0	页次 (PAGE): 1/1	设计 (DESIGN)	柯南
比例 (SCALE) 1:1		模号 (MODEL NO)	审核 (CHECKED) 邱敏		
		图号 (DWG NO)	MLD-2509031032	核准 (APPROVED) 陈镇	